

CLAIM AMENDMENTS

1. (Currently amended) A method for installation of a temperature-sensitive electronic component on a board comprising:

providing a board which has openings for solder connections on an electronic component to pass through,

providing a removable protection apparatus including a thermal insulation layer and a metallic outer coating on an outer wall of the protection apparatus to protect the component during the installation process,

moving the component first so close to the board that the solder connections project through the openings in the board,

connecting the solder connections using a soldering ~~method~~ process to a conductor track which is provided on a side of the board which faces away from the component while thermally coupling the solder connections to the metallic outer coating on the outer wall of the protection apparatus, and

subsequently removing the protection apparatus once the soldering process has been completed,

wherein ~~the component is thermally coupled to the protection apparatus during the soldering process so that~~ some of the heat which is introduced into the solder connections during the soldering process is passed to the protection apparatus.

2. (Canceled)

3. (Original) The method as claimed in claim 1, wherein the solder connections of the component are connected to the board by means of wave soldering.

4-21. (Canceled)

22. (Currently amended) A method according to claim ~~[[18]]~~ 1, wherein said protection apparatus is a bubble, wherein said thermal insulation layer is formed of a plastic layer facing the component with [[a]] the metallic coating on the plastic layer facing away from the component, and wherein said solder connections in use ~~penetrating~~ penetrate the plastic layer with the metallic coating to thereby assure thermal and mechanical coupling of the solder connections with the metallic coating.

23. (Currently amended) A method according to claim 22, wherein said removing includes tearing the bubble layer with the metallic component coating along the solder connections ~~member~~ with perforations formed by the solder connections facilitating said removing.

24. (Currently amended) A method according to claim 23, wherein said component is bonded to ~~[[the]]~~ a plastic layer side of the protection apparatus such that the solder ~~connection members~~ connections pass through the plastic layer and the metallic ~~layer~~ outer coating and edges of said ~~layers~~ plastic layer

and said metallic outer coating are folded around the components to form a closed bubble.

25-32. (Canceled)